Freescale Semiconductor

MP3H6115A
Rev 4, 10/2009

High Temperature Accuracy Integrated Silicon Pressure Sensor for Measuring Absolute Pressure, On-Chip Signal Conditioned, Temperature Compensated and Calibrated

MP3H6115A Series

15 to 115 kPa (2.2 to 16.7 psi)
0.12 to 2.8 V Output

Freescale's MP3H6115A series sensor integrates on-chip, bipolar op amp circuitry and thin film resistor networks to provide a high output signal and temperature compensation. The small form factor and high reliability of on-chip integration make the Freescale pressure sensor a logical and economical choice for the system designer.

The MP3H6115A series piezoresistive transducer is a state-of-the-art, monolithic, signal conditioned, silicon pressure sensor. This sensor combines advanced micromachining techniques, thin film metallization, and bipolar semiconductor processing to provide an accurate, high level analog output signal that is proportional to applied pressure.

Application Examples

- Aviation Altimeters
- Industrial Controls
- Engine Control/Manifold Absolute Pressure (MAP)
- Weather Station and Weather Reporting Device Barometers

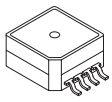
Features

- Improved Accuracy at High Temperature
- Available in Super Small Outline Package
- 1.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated from -40° to +125°C
- Durable Thermoplastic (PPS) Surface Mount Package

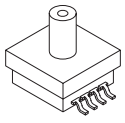
ORDERING INFORMATION

Device Name	Packaging Options	Case No.	# of Ports			Pressure Type			Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
Super Small Outline Package (MP3H6115A Series)									
MP3H6115A6U	Rail	1317	•					•	MP3H6115A
MP3H6115A6T1	Tape & Reel	1317	•					•	MP3H6115A
MP3H6115AC6U	Rail	1317A		•				•	MP3H6115A
MP3H6115AC6T1	Tape & Reel	1317A		•				•	MP3H6115A

SUPER SMALL OUTLINE PACKAGES



MP3H6115A6U/T1
CASE 1317-04



MP3H6115AC6U/T1
CASE 1317A-04

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Operating Characteristics

Table 1. Operating Characteristics

(V_S = 3.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range		P_{OP}	15	—	115	kPa
Supply Voltage(1)		V_S	2.7	3.0	3.3	Vdc
Supply Current		I_o	—	4.0	8.0	mAdc
Minimum Pressure Offset(2) @ V_S = 3.0 Volts	(0 to 85°C)	V_{off}	0.079	0.12	0.161	Vdc
Full Scale Output(3) @ V_S = 3.0 Volts	(0 to 85°C)	V_{FSO}	2.780	2.82	2.861	Vdc
Full Scale Span(4) @ V_S = 3.0 Volts	(0 to 85°C)	V_{FSS}	2.660	2.70	2.741	Vdc
Accuracy	(0 to 85°C)	—	—	—	±1.5	$\%V_{FSS}$
Sensitivity		V/P	—	27	—	mV/kPa
Response Time(5)		t_R	—	1.0	—	ms
Warm-Up Time(6)		—	—	20	—	ms
Offset Stability(7)		—	—	±0.25	—	$\%V_{FSS}$

1. Device is ratiometric within this specified excitation range.
2. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
3. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
4. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
5. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
6. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the pressure has been stabilized.
7. Offset Stability is the product's output deviation when subjected to 1000 cycles of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings(1)

Parametrics	Symbol	Value	Units
Maximum Pressure (P1 > P2)	P_{max}	400	kPa
Storage Temperature	T_{stg}	-40° to +125°	°C
Operating Temperature	T_A	-40° to +125°	°C
Output Source Current @ Full Scale Output(2)	I_o+	0.5	mAdc
Output Sink Current @ Minimum Pressure Offset(2)	I_o-	-0.5	mAdc

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.
2. Maximum Output Current is controlled by effective impedance from V_{out} to Gnd or V_{out} to V_S in the application circuit.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

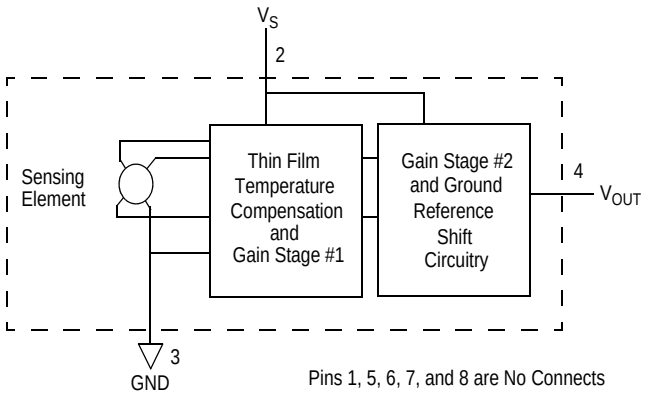


Figure 1. Fully Integrated Pressure Sensor Schematic

On-chip Temperature Compensation and Calibration

Figure 2 illustrates the absolute sensing chip in the basic Super Small Outline chip carrier (Case 1317).

Figure 3 shows a typical application circuit (output source current operation).

Figure 4 shows the sensor output signal relative to pressure input. Typical minimum and maximum output curves are shown for operation over 0 to 85°C temperature range. The output will saturate outside of the rated pressure range.

A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm. The MP3H6115A series pressure sensor operating characteristics, internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

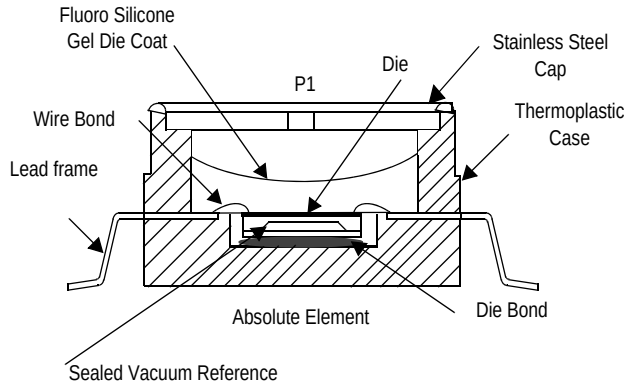


Figure 2. Cross Sectional Diagram SSOP (not to scale)

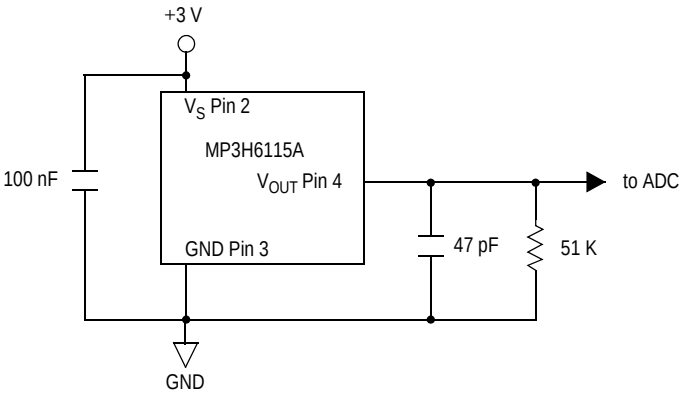


Figure 3. Typical Application Circuit (Output Source Current Operation)

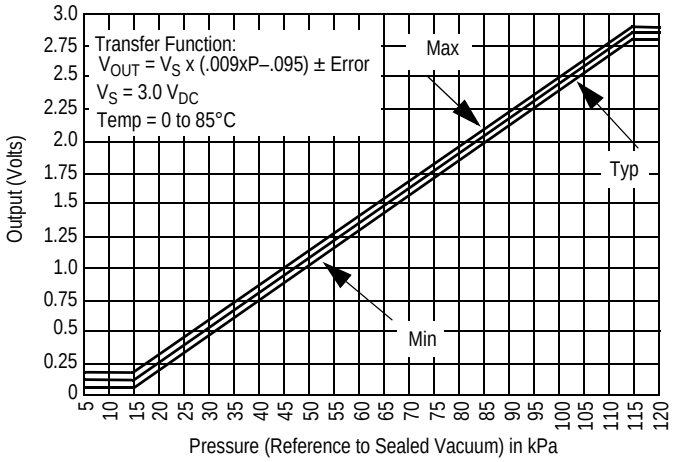
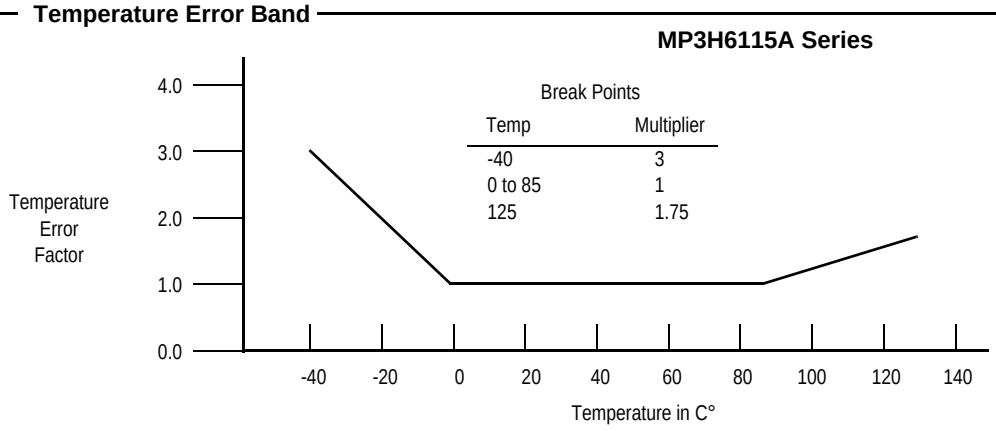


Figure 4. Output versus Absolute Pressure

Transfer Function (MP3H6115A)

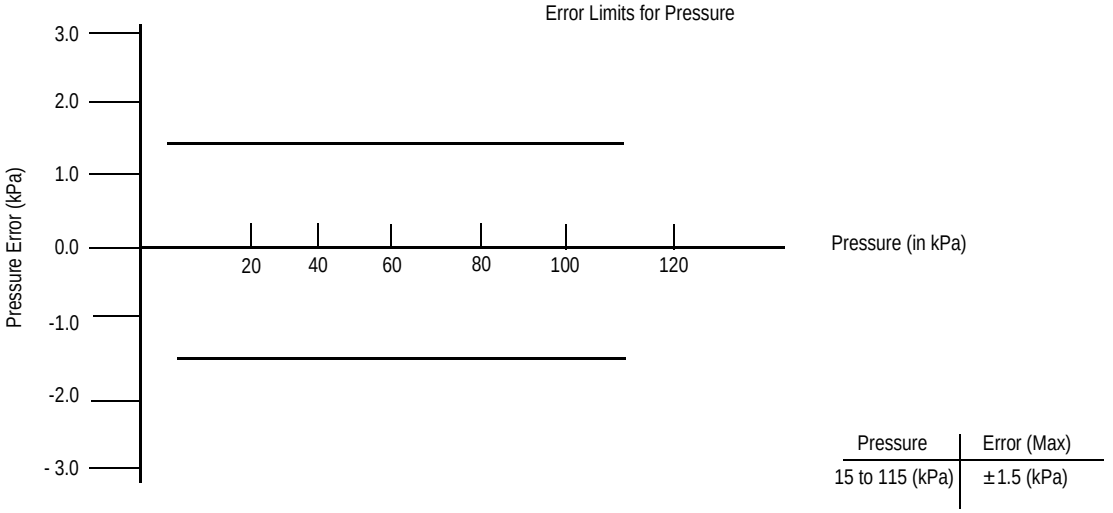
Normal Transfer Value: $V_{OUT} = V_S \times (0.009 \times P - 0.095)$
$\pm$ (Pressure Error x Temp. Factor x 0.009 x V_S)
$V_S = 3.0 \pm 0.3\ V_{DC}$

Temperature Error Band



NOTE: The Temperature Multiplier is a linear response from 0°C to -40°C and from 85°C to 125°C

Pressure Error Band



Pressure	Error (Max)
15 to 115 (kPa)	±1.5 (kPa)

MINIMUM RECOMMENDED FOOTPRINT FOR SMALL AND SUPER SMALL PACKAGES

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor package must be the correct size to ensure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self-align when subjected to a solder reflow process. It is always recommended to fabricate boards with a solder mask layer to avoid bridging and/or shorting between solder pads, especially on tight tolerances and/or tight layouts.

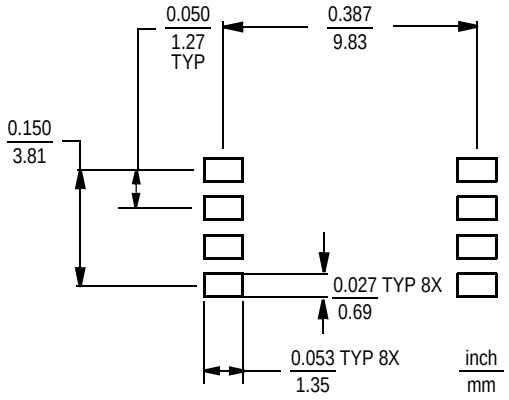
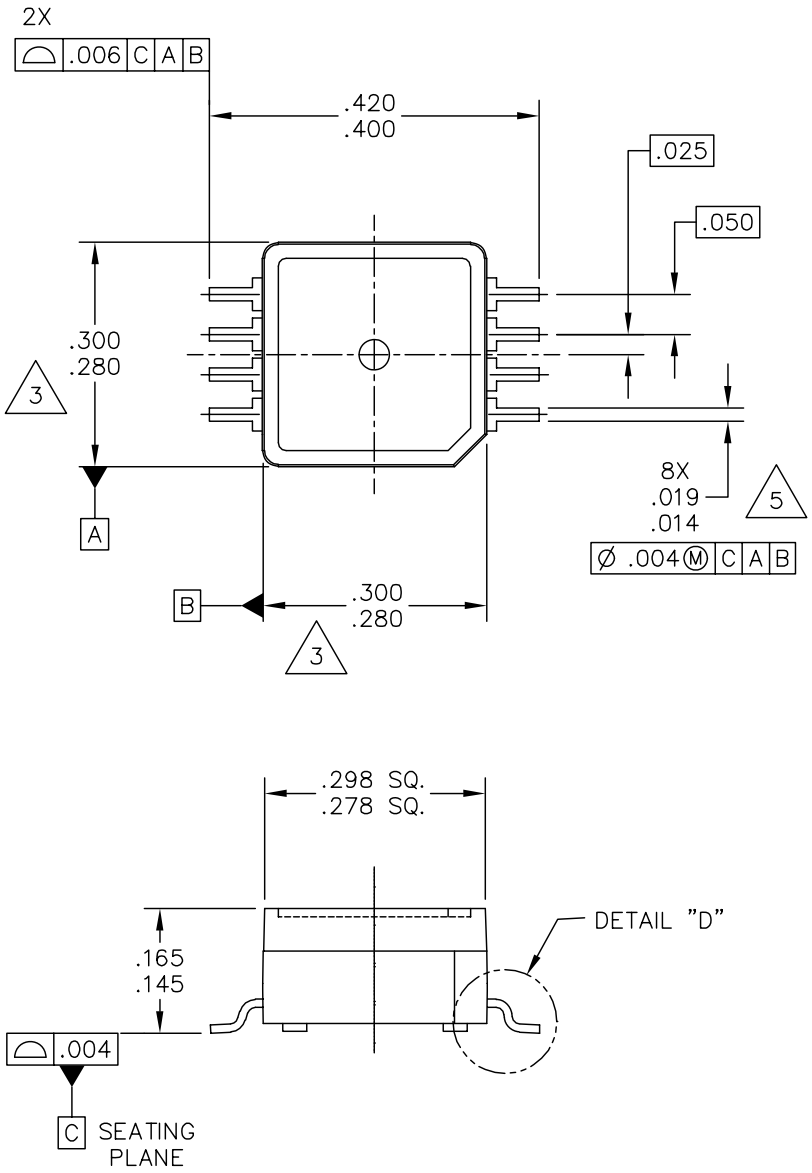


Figure 5. SSOP Footprint (Case 1317 and 1317A)

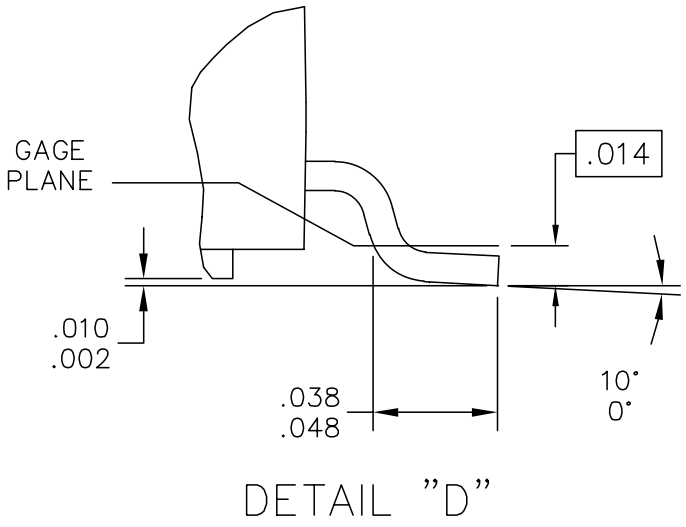
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	CASE NUMBER: 1317–04	24 MAY 2005
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CASE 1317-04
ISSUE F
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PACKAGE DIMENSIONS



DETAIL "D"

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4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
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   ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

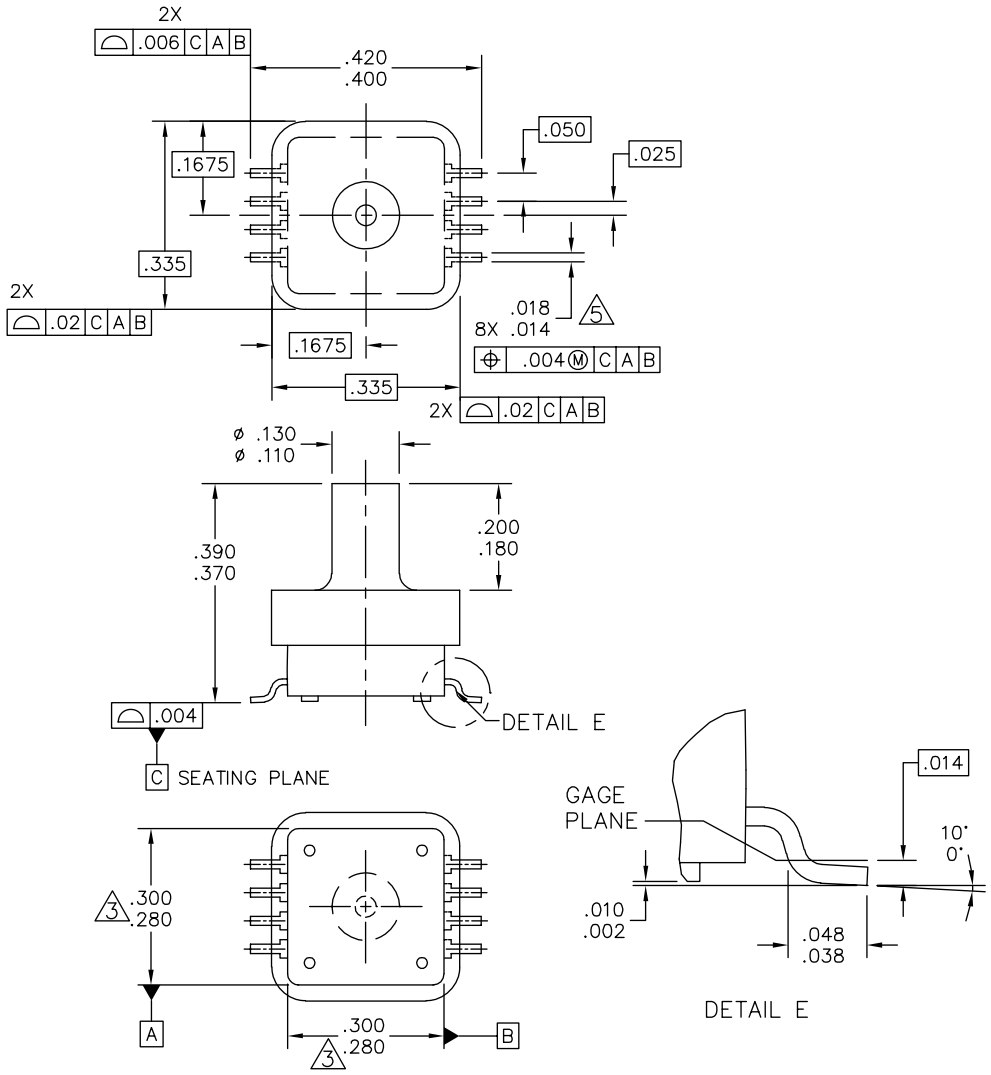
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CASE 1317A-04
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